

MA26V01

Silicon epitaxial planar type

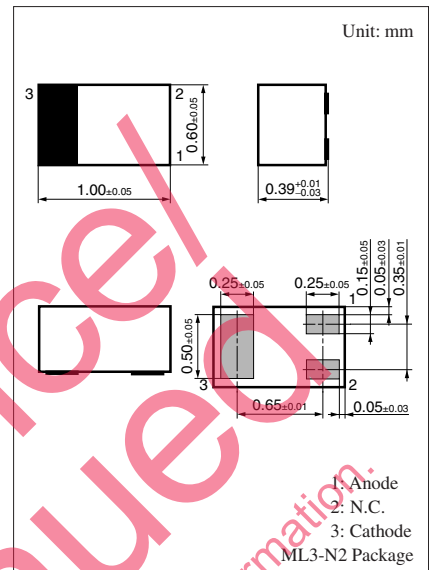
For VCO

■ Features

- Good linearity and large capacitance-ratio in $C_D - V_R$ relation
- Small series resistance r_D

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	6	V
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



Marking Symbol: 2D

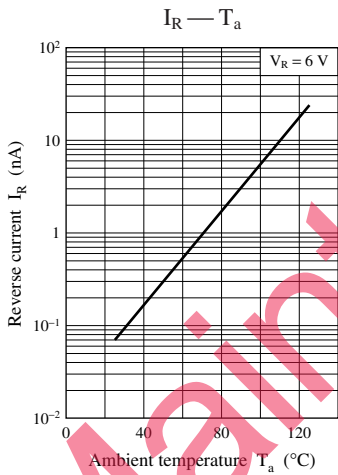
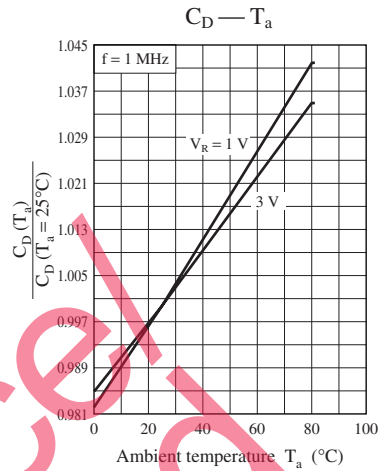
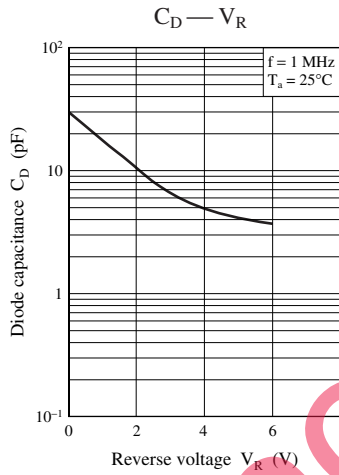
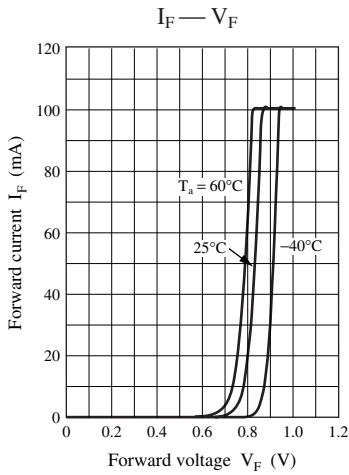
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	I_R	$V_R = 6\text{ V}$			10	nA
Diode capacitance	C_{D1V}	$V_R = 1\text{ V}, f = 1\text{ MHz}$	15.0		17.0	pF
	C_{D3V}	$V_R = 3\text{ V}, f = 1\text{ MHz}$	5.0		7.0	
Capacitance ratio	C_{D1V}/C_{D3V}		2.2			—
Series resistance *	r_D	$C_D = 9\text{ pF}, f = 470\text{ MHz}$			1.0	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 470 MHz.

3. *: Measuring instrument: YHP MODEL 4191A RF IMPEDANCE ANALYZER



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